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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

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CONFIRMATION NO.: 3742

APPLICANT: Narendar et al.

GROUP ART UNIT: 1755

EXAMINER: Karl E. Group

U.S. PATENT DOCUMENTS

Examiner's Initials	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication or of issue of Cited Document MM-DD-YYYY
		Number	Kind Code		
		*5,834,387		Divakar et al.	11-10-1998

FOREIGN PATENT DOCUMENTS

Examiner's Initials	Cite No.	Foreign Patent Document			Name of Patentee or Applicant of Cited Document (not necessary)	Date of Publication of Cited Document MM-DD-YYYY	Translation (Y/N)
		Office/Country	Number	Kind Code			
		EP	1 184 355	A1	Toshiba Ceramics Co., Ltd.	03-06-2002	
		JP	2002 338366	A	Tokai Konetsu Kogyo Co., Ltd.	11-27-2002	Abstract
		CA	2 466 183	A1	Bridgestone Corporation, JP	05-15-2003	

OTHER ART – NON PATENT LITERATURE DOCUMENTS

Examiner's Initials	Cite No	Include name of the author (in CAPITAL LETTERS) title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, relevant page(s), volume-issue number(s), publisher, city and/or country where published.	Translation (Y/N)
		H. RAUH, "Atlas for Characterization of Defects in Silicon," Wacker Siltronic AG, Burghausen, Germany, pp. 1-64, 2004.	
		R. F. BUCKLEY et al., "Design and Analysis of a Semiconductor Wafer Processing System for 30 mm Wafers," MS Thesis submitted to the Worcester Polytechnic Institute, 12/22/99, pp. i-62.	
		B. LEROY et al., "Warpage of Silicon Wafers," <i>Journal Electrochemical Society</i> , Vol. 127, No. 4, April 1980, pp. 961-970.	
		M. SCHREMS et al., "Simulation of Temperature Distributions During Fast Thermal Processing," <i>Journal Electrochemical Society</i> , Semiconductor Silicon 1994, pp. 1050-1059.	
		NILSON et al., "Scaling wafer stresses and thermal processes to large wafers," <i>Thin Solid Films</i> 315, 1998, pp. 286-293.	
		PETER VAN ZANT, "Microchip Fabrication: A Practical Guide to Semiconductor Processing," McGraw Hill, Fourth Edition, 1990, chapters 3-7.	
		SHIGLEY et al., "Mechanical Engineering Design," McGraw Hill, copyright 1989, p. 62, p. 159.	
		Machinery Handbook, 24 th Edition, Industrial Press, Copyright 1992, pp. 1598-1603.	

EXAMINER

DATE CONSIDERED

12/7/05

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*a copy of this reference is not provided because a copy of this reference need not be provided as the reference is a published U.S. Patent or U.S. Patent application and the present application was filed after June 30, 2003.